



Subject: PCN: SAW VCSO Assembly Process Change
VI-CN-070212

Date: February 12, 2007

From: Joe Beauchemin
Tel: 603-577-6811

NOTE: This PCN is intended to be a general PCN for all customers. Key customers will be notified through direct communication. VI will also post a copy on the VI Web-site (<http://www.vectron.com>) for the benefit of customers with small orders/infrequent order history or those that indirectly procure affected VI product through distribution channels.

To:
All Customers:

This PCN affects the VS-550 Vectron SAW oscillator product built in the Hudson, NH facility.

Vectron plans to introduce an internal process change starting Q1/07 to change the assembly adhesive in the VS-550 product. The current adhesive Ablebond® 84-1-LMI-NB-1 is being replaced with the Ablebond® 71-1. The Ablebond® 71-1 has been qualified by VI and is in use for other SAW oscillator products and high temperature and high reliability applications..

The change involves the use of the new adhesive for making the electrical connections between the substrate and the package pads. Vectron has found that the new adhesive is optimally suited for electrical connections in high frequency RF devices, such as the SAW oscillators, where stability of joint impedance under sustained high temperatures is needed for long-term reliability. The 71-1 is a silver-filled polyimide material, which is typically processed at high cure temperatures resulting in high glass transition temperatures. Other adhesives currently used in the assembly of the VS-550 product, and the overall assembly/manufacturing process remains unchanged.

VI-Hudson has qualified this change and customers should see no effect on the product fit, form or function as a result of this change. This PCN is therefore being communicated for notification only.

If you need any additional information regarding this change, please contact your VI Marketing & Sales Representative or contact:

Mr. Paul Taylor
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Mr. Joe Beauchemin
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CUSTOMER NOTIFICATION OF PROPOSED PRODUCT/PROCESS CHANGE

CPN Number: VI-CN-070212 VI Location Requesting
 Date: Feb. 12, 2007 Change:
 Customer Approval: MHS NBH TFT PDG HUD
 Required: _____ Information Only X

Product Code(s)/Families: VS-550 SAW-based VCSO oscillator product family manufactured by VI.
 Part Numbers: various

Project/Application: various

Customer (s)/Location(s): _____
 Description of Change: Change of adhesive from Ablebond® 84-1-LMI-NB-1 to Ablebond® 71-1 for the attachment of the internal substrate to the ceramic package

Effects of Change to:

Appearance: No change

Product Identification: None.

Test Specification: None.

Performance Parameters: None.

Reliability: Improved electrical connectivity between the substrate and the package pads under sustained high operating temperatures from the use of a polyimide-based adhesive

Sample Availability Date: N/A

Estimated Shipment Date: Production ramp-up starting in 1Q2007

Requested Customer Response Date: N/A

Product Manager: P. Taylor Tel.: 603-577-3005 Fax.: 603-598-0075

Respond to: J. Beauchemin Tel.: 603-577-6811 Fax.: 603-577-6876

CPN No.: VI-CN-070212	Change Description Change substrate attachment adhesive to 71-1	Issue: 1	Date: 2/12/07
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